

Title (en)
Connector for a printed circuit board

Title (de)
Leiterplattensteckverbindung

Title (fr)
Connecteur pour plaque à circuit intégré

Publication
EP 1168526 A3 20040121 (DE)

Application
EP 01113560 A 20010613

Priority
DE 10029925 A 20000617

Abstract (en)
[origin: EP1168526A2] The device has a conducting foil attached to a first connector body with one connection end on the opposite side of the body from a board and another between a first connector application surface and the board with conducting tracks facing board contact areas. A second connector body has an insulating housing slot with contacts into which the foil penetrates when the connectors are joined to connect the contacts and the foil's conducting tracks. The device has first connector (1) with an insulating body (10) and a plug region with contact sockets and a second connector (2) with an insulating body (20) and a plug region with contact pins, each attached to a circuit board. A conducting foil (3) attached to the first connector's insulating body has a first connection end on the opposite side of the body from the board and a second connection end between a first connector application surface and the board with conducting tracks facing contact areas on the board. The second connector's insulating body has an insulating housing with a slot (24) containing contacts (25) and into which the foil penetrates when the connectors are joined to bring the contacts into electrical contact with the foil's conducting tracks.

IPC 1-7
H01R 12/20

IPC 8 full level
H01R 12/14 (2006.01); **H01R 12/16** (2006.01); **H01R 12/20** (2006.01); **H01R 12/24** (2006.01); **H01R 12/28** (2006.01); **H01R 12/50** (2011.01); **H01R 12/71** (2011.01); **H01R 12/72** (2011.01); **H01R 12/73** (2011.01); **H01R 13/46** (2006.01); **H01R 13/658** (2006.01); **H05K 1/14** (2006.01); **H05K 5/00** (2006.01); **H05K 5/04** (2006.01); **H05K 5/06** (2006.01)

CPC (source: EP US)
H01R 12/716 (2013.01 - EP US); **H01R 12/722** (2013.01 - EP US); **H01R 12/737** (2013.01 - EP US)

Citation (search report)

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- [A] EP 0395051 A2 19901031 - SIEMENS AG [DE]
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Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)
EP 1168526 A2 20020102; **EP 1168526 A3 20040121**; **EP 1168526 B1 20050427**; CA 2350289 A1 20011217; CA 2350289 C 20041130; CN 1148839 C 20040505; CN 1330432 A 20020109; DE 10029925 C1 20020110; DE 50106003 D1 20050602; JP 2002025658 A 20020125; JP 3437842 B2 20030818; US 2002051347 A1 20020502; US 6434014 B1 20020813

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